

Complementary 20-V (D-S) Low-Threshold MOSFET

PRODUCT SUMMARY			
	V _{DS} (V)	r _{DS(on)} (Ω)	I _D (A)
N-Channel	20	0.280 at V _{GS} = 4.5 V	1.28
		0.360 at V _{GS} = 2.5 V	1.13
		0.450 at V _{GS} = 1.8 V	1.0
P-Channel	- 20	0.490 at V _{GS} = - 4.5 V	- 1.0
		0.750 at V _{GS} = - 2.5 V	- 0.81
		1.10 at V _{GS} = - 1.8 V	- 0.67

FEATURES

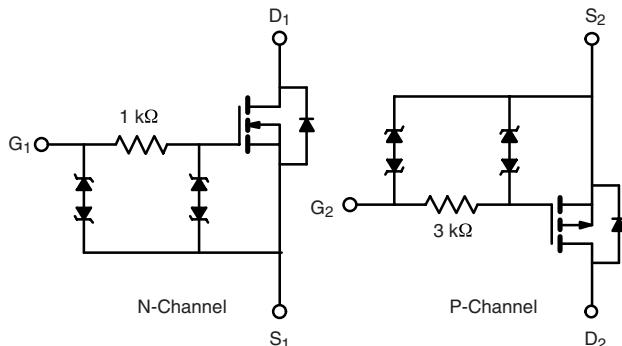
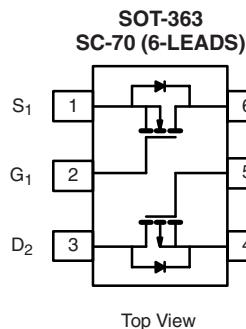
- TrenchFET® Power MOSFETs: 1.8 V Rated
- ESD Protected: 2000 V
- Thermally Enhanced SC-70 Package



Pb-free
Available
RoHS*
COMPLIANT

APPLICATIONS

- Load Switching
- PA Switch
- Level Switch



Ordering Information: Si1563EDH-T1
Si1563EDH-T1-E3 (Lead (Pb)-free)

ABSOLUTE MAXIMUM RATINGS T_A = 25 °C, unless otherwise noted

Parameter	Symbol	N-Channel		P-Channel		Unit
		5 s	Steady State	5 s	Steady State	
Drain-Source Voltage	V _{DS}	20		- 20		
Gate-Source Voltage	V _{GS}	± 12		± 12		V
Continuous Drain Current (T _J = 150 °C) T _A = 25 °C	I _D	1.28	1.13	- 1.0	- 0.88	A
		0.92	0.81	- 0.72	- 0.63	
Pulsed Drain Current	I _{DM}	4.0		- 3.0		
Continuous Source Current (Diode Conduction) ^a	I _S	0.61	0.48	- 0.61	- 0.48	
Maximum Power Dissipation ^a T _A = 25 °C	P _D	0.74	0.57	0.30	0.57	W
		0.38	0.30	0.16	0.3	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150				°C

THERMAL RESISTANCE RATINGS

Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^a	t ≤ 5 s	R _{thJA}	130	170	°C/W
	Steady State		170	220	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	80	100	

Notes:

a. Surface Mounted on 1" x 1" FR4 Board.

* Pb containing terminations are not RoHS compliant, exemptions may apply.

SPECIFICATIONS $T_J = 25^\circ\text{C}$, unless otherwise noted

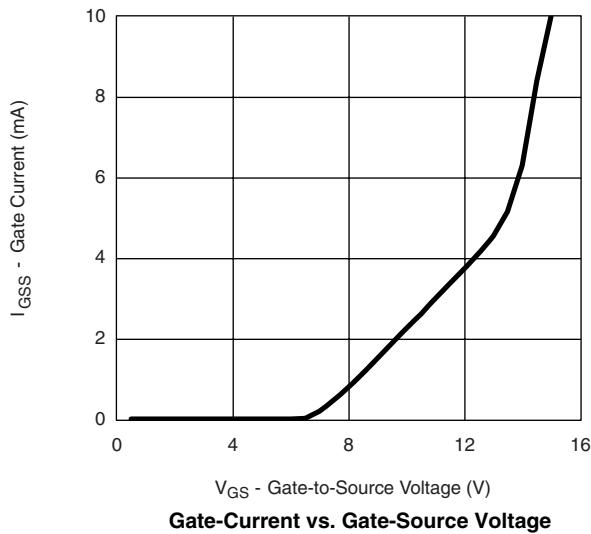
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 100 \mu\text{A}$	N-Ch	0.45		
		$V_{DS} = V_{GS}, I_D = -100 \mu\text{A}$	P-Ch	- 0.45		
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$	N-Ch		± 1	μA
		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$	P-Ch		± 1	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 16 \text{ V}, V_{GS} = 0 \text{ V}$	N-Ch		1	μA
		$V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V}$	P-Ch		- 1	
		$V_{DS} = 16 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 85^\circ\text{C}$	N-Ch		5	
		$V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 85^\circ\text{C}$	P-Ch		- 5	
On-State Drain Current ^a	$I_{D(\text{on})}$	$V_{DS} \geq 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	N-Ch	2		A
		$V_{DS} \leq -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	P-Ch	- 2		
Drain-Source On-State Resistance ^a	$r_{DS(\text{on})}$	$V_{GS} = 4.5 \text{ V}, I_D = 1.13 \text{ A}$	N-Ch		0.220	0.280
		$V_{GS} = -4.5 \text{ V}, I_D = -0.88 \text{ A}$	P-Ch		0.400	0.490
		$V_{GS} = 2.5 \text{ V}, I_D = 0.99 \text{ A}$	N-Ch		0.281	0.360
		$V_{GS} = -2.5 \text{ V}, I_D = -0.71 \text{ A}$	P-Ch		0.610	0.750
		$V_{GS} = 1.8 \text{ V}, I_D = 0.20 \text{ A}$	N-Ch		0.344	0.450
		$V_{GS} = -1.8 \text{ V}, I_D = -0.20 \text{ A}$	P-Ch		0.850	1.10
Forward Transconductance ^a	g_{fs}	$V_{DS} = 10 \text{ V}, I_D = 1.13 \text{ A}$	N-Ch		2.6	S
		$V_{DS} = -10 \text{ V}, I_D = -0.88 \text{ A}$	P-Ch		1.5	
Diode Forward Voltage ^a	V_{SD}	$I_S = 0.48 \text{ V}, V_{GS} = 0 \text{ V}$	N-Ch		0.8	1.2
		$I_S = -0.48 \text{ V}, V_{GS} = 0 \text{ V}$	P-Ch		- 0.8	- 1.2
Dynamic^b						
Total Gate Charge	Q_g	N-Channel $V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 1.13 \text{ A}$ P-Channel $V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_D = -0.88 \text{ A}$	N-Ch		0.65	1.0
Gate-Source Charge	Q_{gs}		P-Ch		1.2	1.8
Gate-Drain Charge	Q_{gd}		N-Ch		0.2	
Turn-On Delay Time	$t_{d(\text{on})}$		P-Ch		0.3	
Rise Time	t_r		N-Ch		0.23	
Turn-Off Delay Time	$t_{d(\text{off})}$		P-Ch		0.3	
Fall Time	t_f	N-Channel $V_{DD} = 10 \text{ V}, R_L = 20 \Omega$ $I_D \cong 0.5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 6 \Omega$ P-Channel $V_{DD} = -10 \text{ V}, R_L = 20 \Omega$ $I_D \cong -0.5 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 6 \Omega$	N-Ch		45	70
			P-Ch		150	230
			N-Ch		85	130
			P-Ch		480	720
			N-Ch		350	530
			P-Ch		840	1200
		N-Channel $V_{DD} = 10 \text{ V}, R_L = 20 \Omega$ $I_D \cong 0.5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 6 \Omega$ P-Channel $V_{DD} = -10 \text{ V}, R_L = 20 \Omega$ $I_D \cong -0.5 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 6 \Omega$	N-Ch		210	320
			P-Ch		850	1200

Notes:

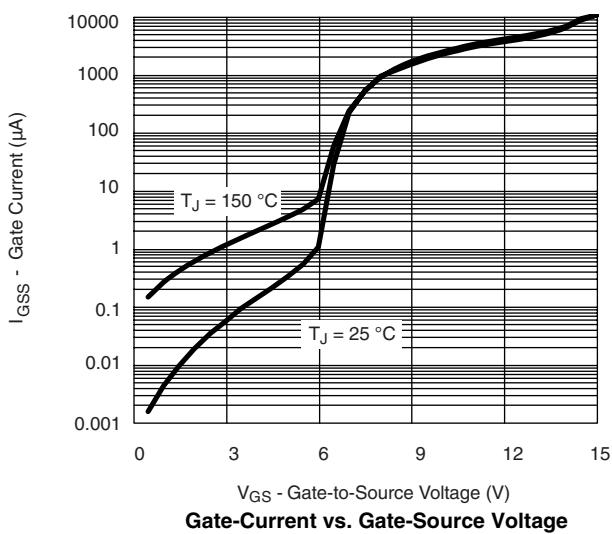
a. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.

b. Guaranteed by design, not subject to production testing.

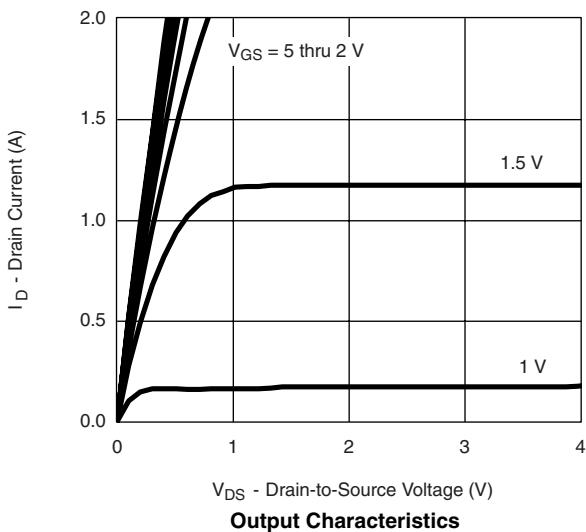
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**N-CHANNEL TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted

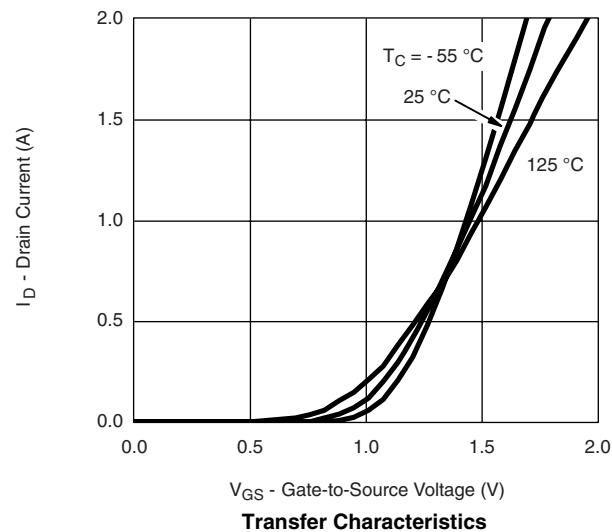
Gate-Current vs. Gate-Source Voltage



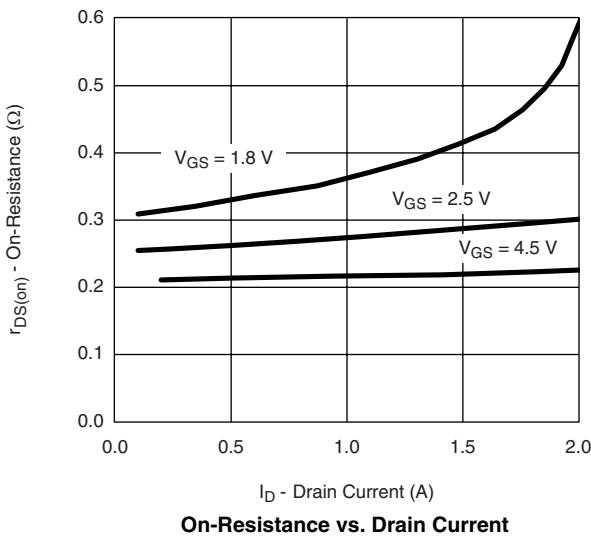
Gate-Current vs. Gate-Source Voltage



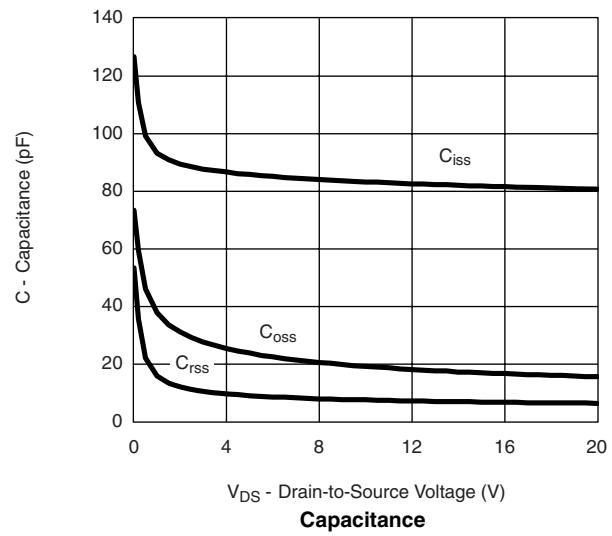
Output Characteristics



Transfer Characteristics



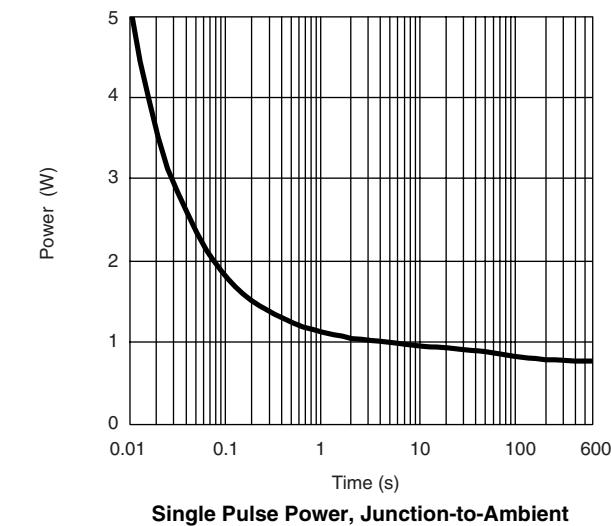
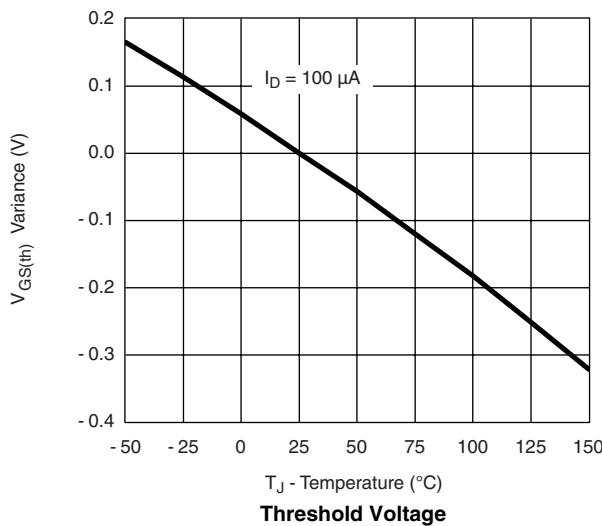
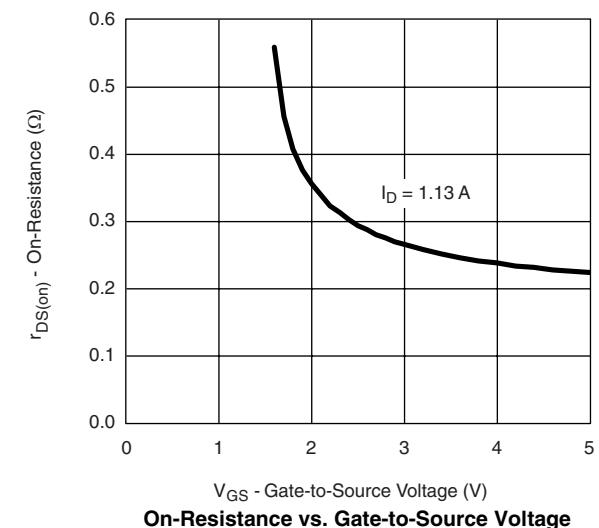
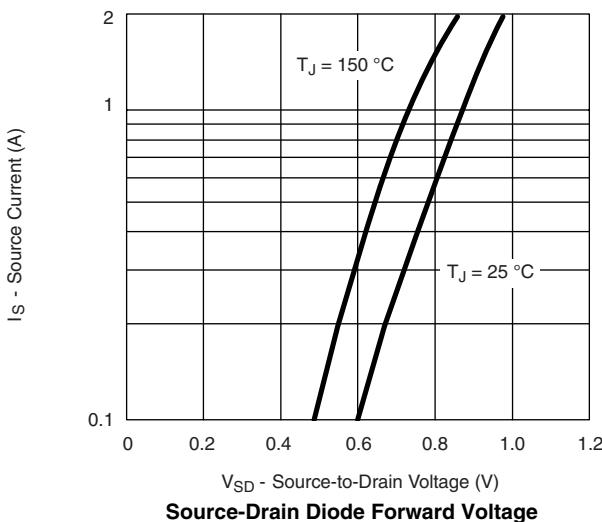
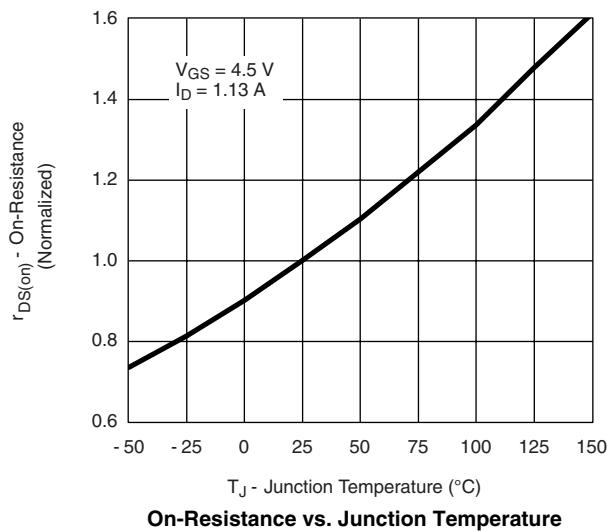
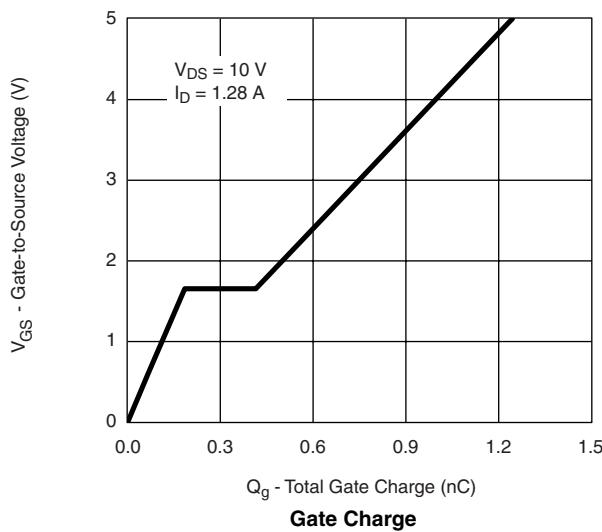
On-Resistance vs. Drain Current

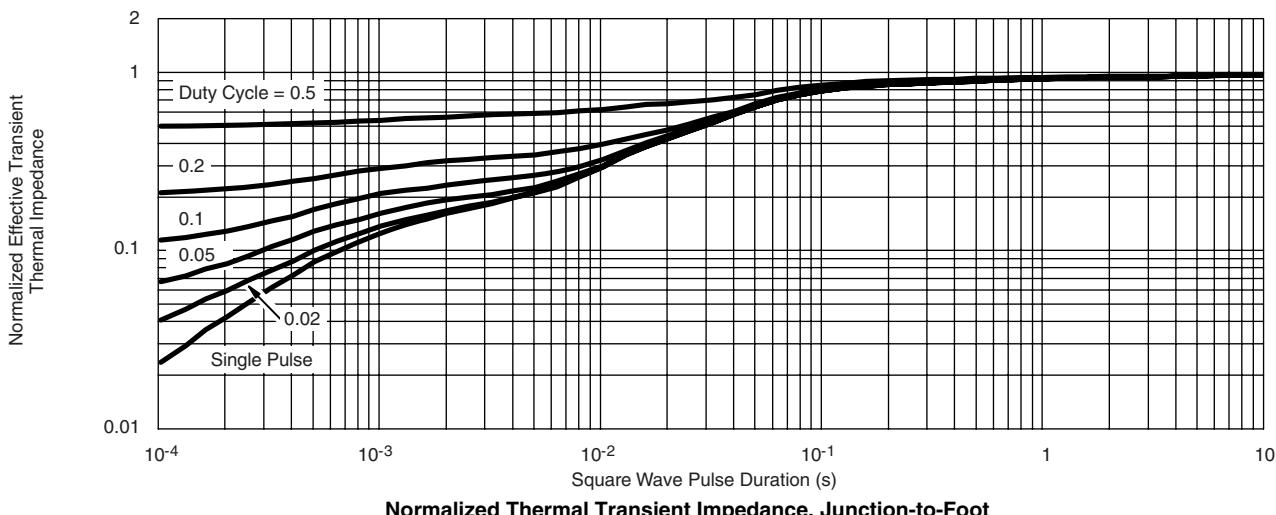
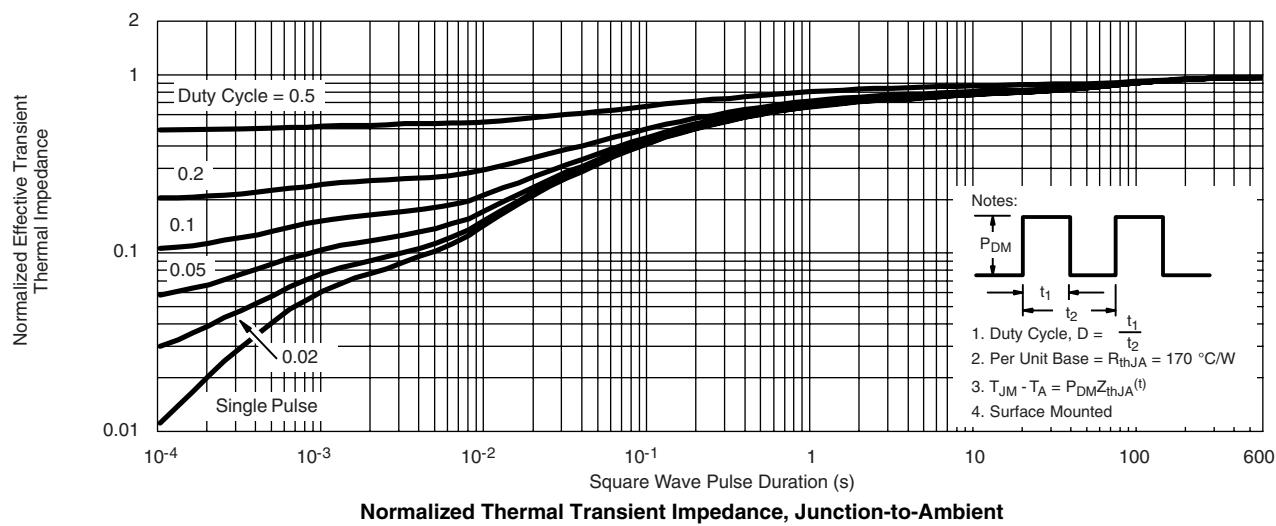


Capacitance

Si1563EDH

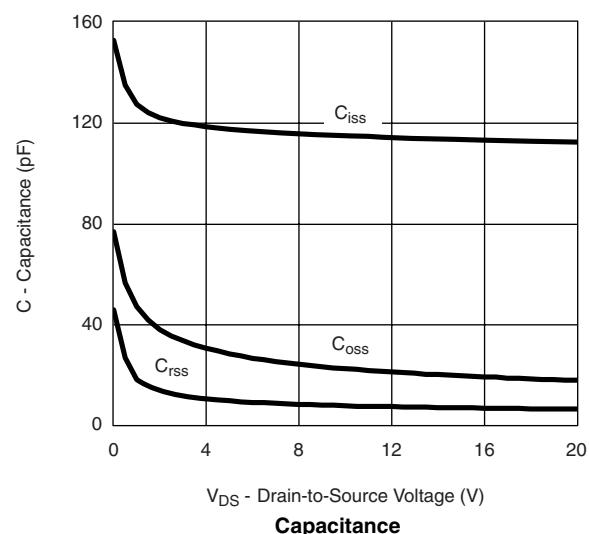
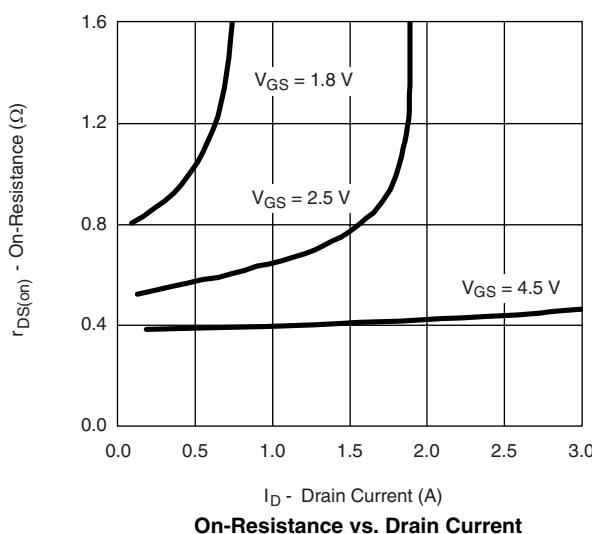
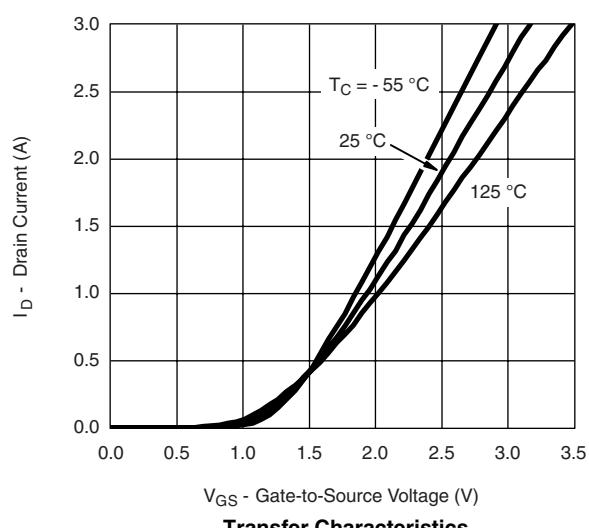
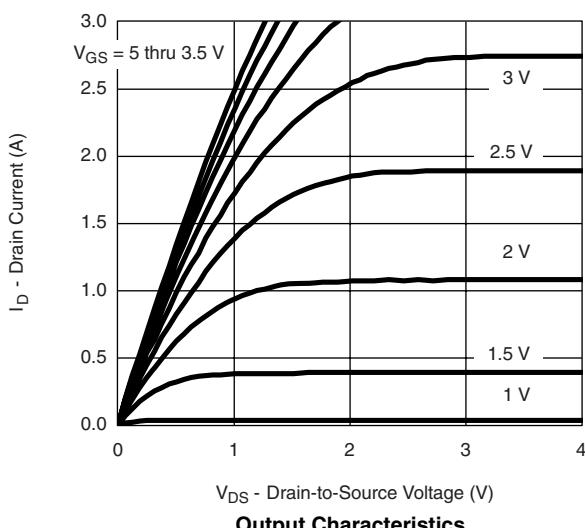
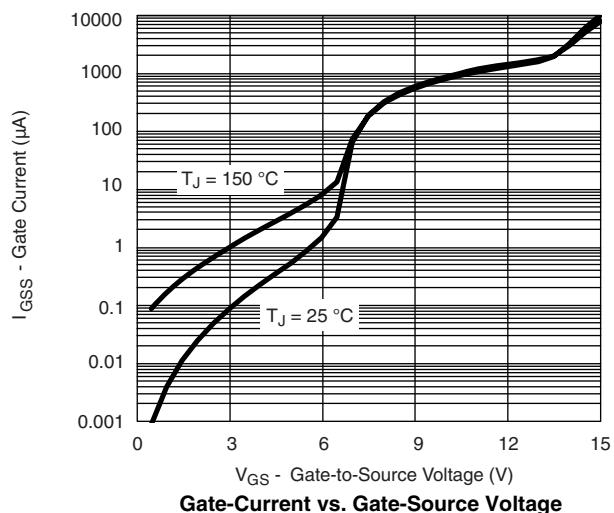
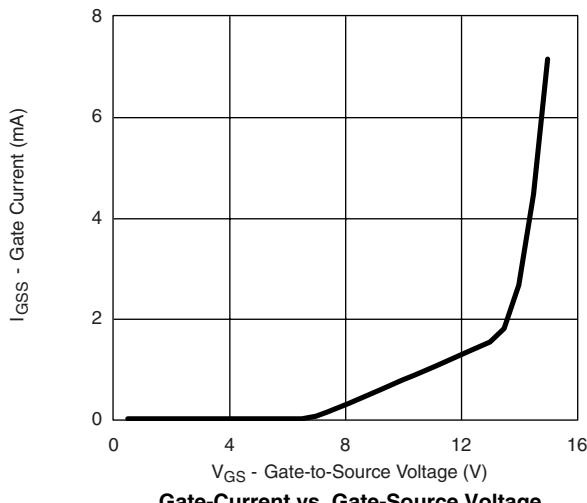
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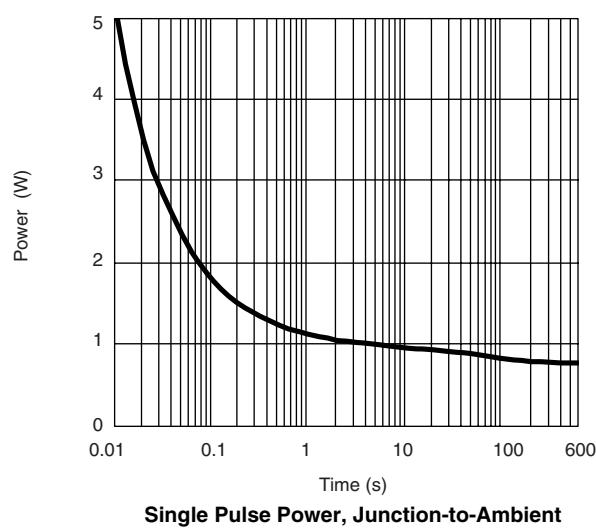
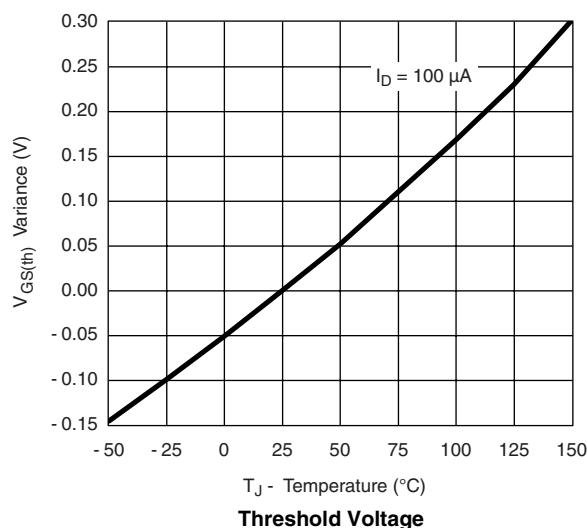
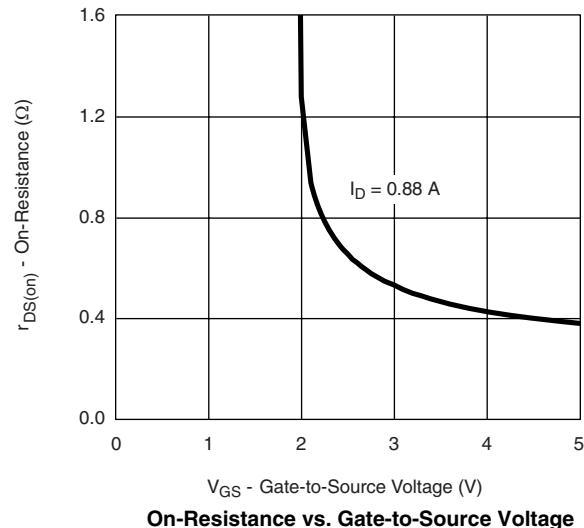
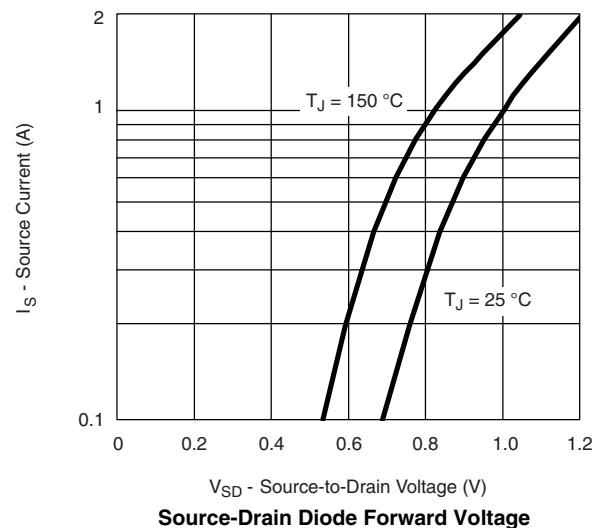
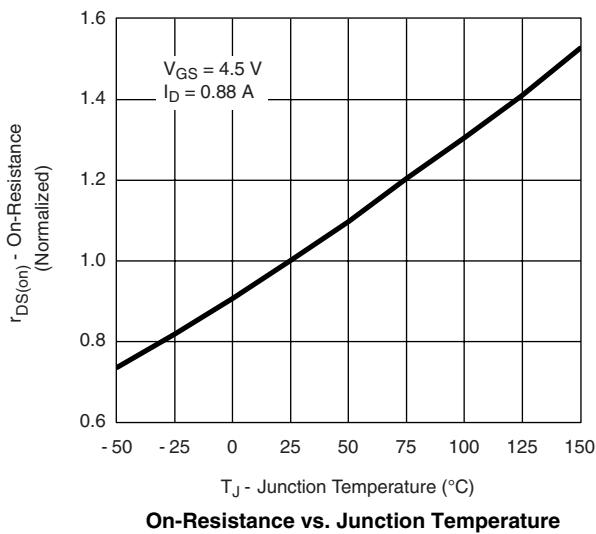
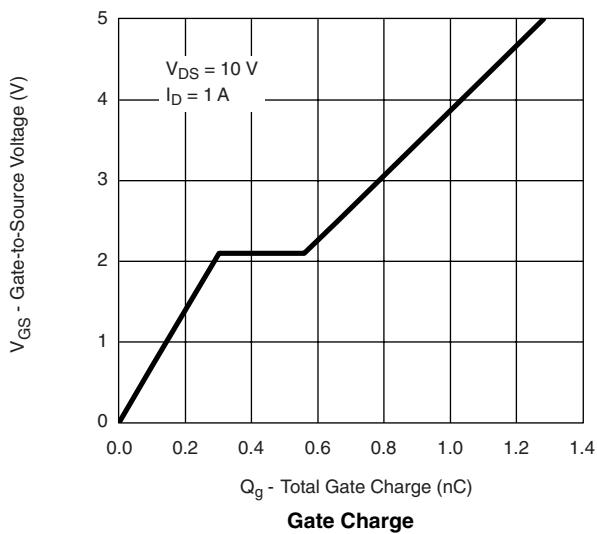
**N-CHANNEL TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted

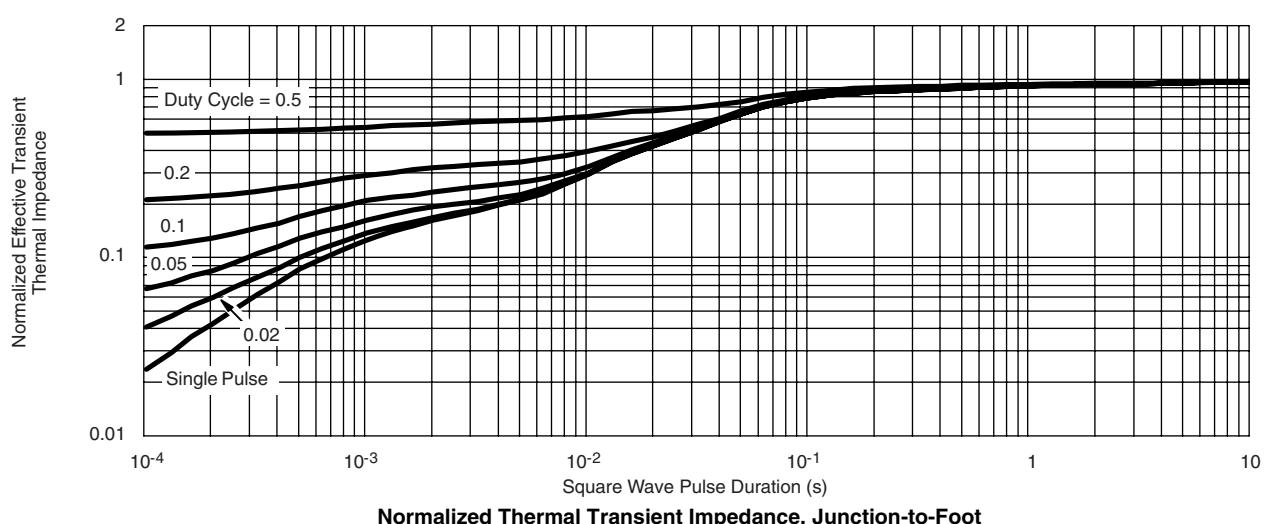
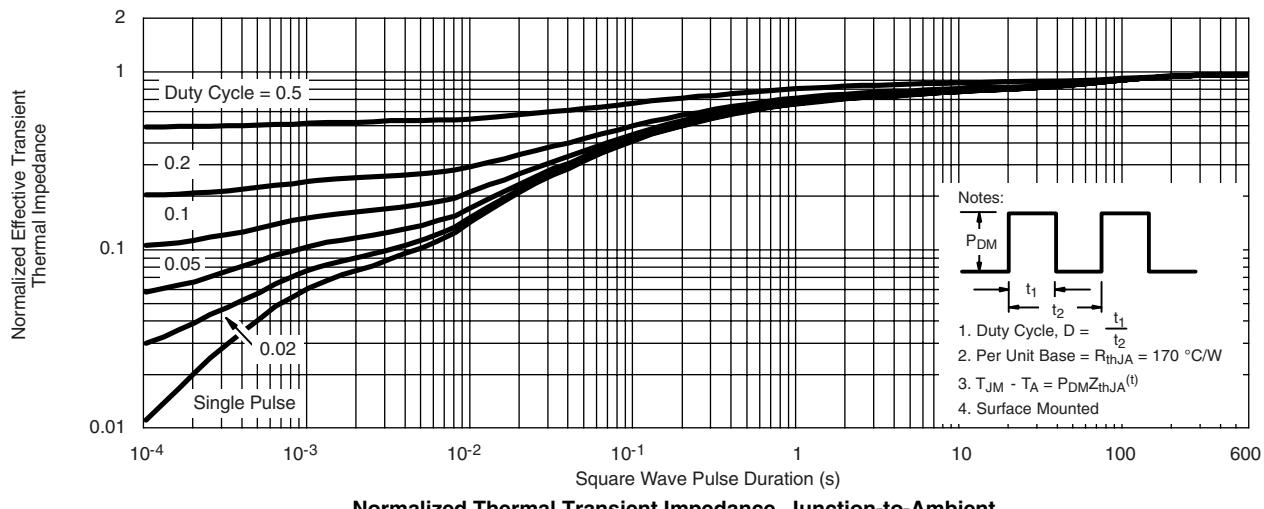
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**P-CHANNEL TYPICAL CHARACTERISTICS** 25 °C, unless otherwise noted

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